Forschungszentrum Karlsruhe
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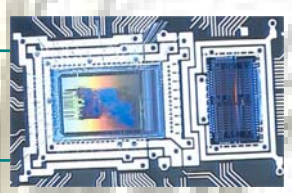


Packaging Technology for the ALICE Transition Radiation Detector

Thomas Blank, Hartmut Gemmeke

Why IPE?
What's the task?
Where's the problem?
What we learn for packaging?

Centre for packaging since 2001

Batch production for hybrid micro-systems

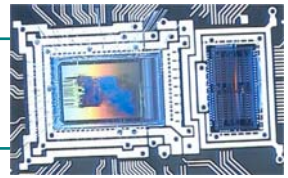
160 m² gray room

SMD production line:
picker&placer,
vapour solder oven,
automatic needle tester,
tests, repair

140 m² clean room
class 100 000 (measured 5000**)**

... **for batch production and R&D of hybrid micro-systems (packaging):**

e.g. vibration sensor,
micro-spectrometer,
electronic gas sensors,
ALICE, …



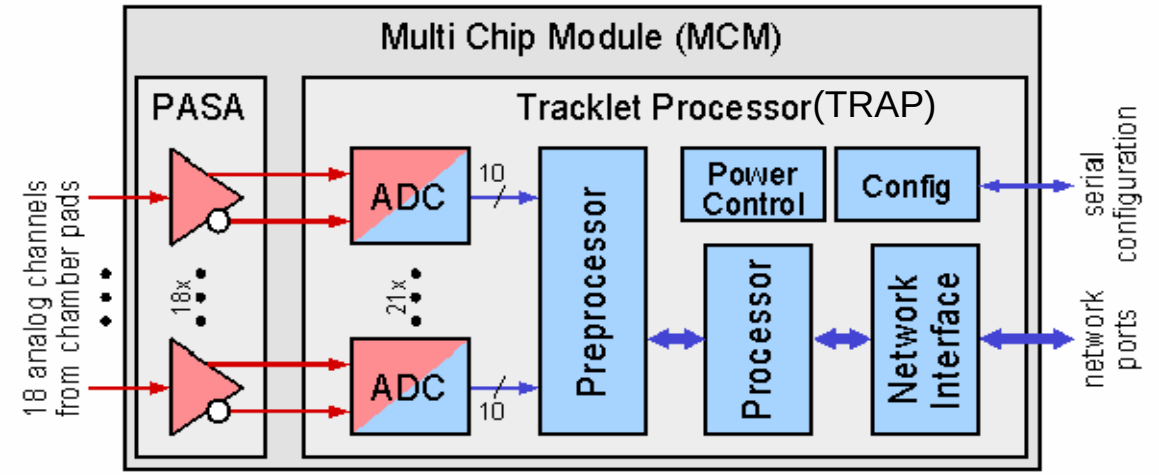
Task for transition radiation detector

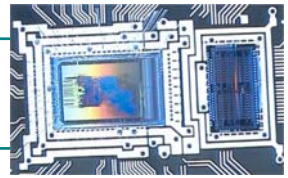
- **High data rate: 15.7 TBd**
- **$1.2*10^6$ data sources**
- **Tracking up to 16 000 charged particles**
- Manageable connectivity -> **data reduction**

Chip farm at frontend

Packaging of chips as thin as possible

2 chips integrated in one Multi-Chip Module
serving 18 analogue channels
16 + 1 MCM's for one readout board





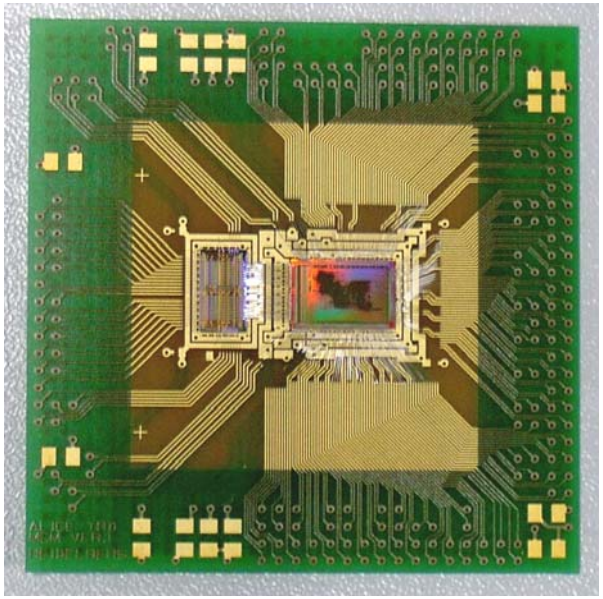
Where is the problem for packaging ???

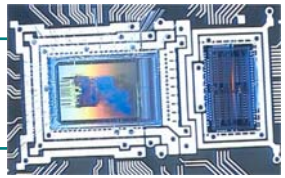
- **65664 ball bonded MCM's**
- **Each MCM with 432 balls and 460 wire bonds,** 30 000 000 balls and 60 000 000 bonds
- **bonds connecting different height levels**
- **very thin (<1mm) printed circuit boards** for **MCM** and **read-out board**
- Should cost "nothing"

yield of production

warpage

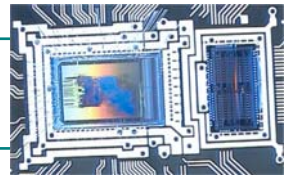
Size 41∗41 mm^2





Processing steps for MCM

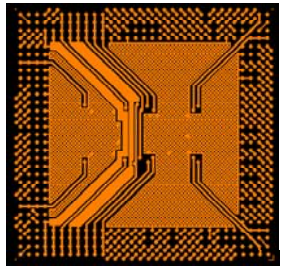
- Optimization of PCB parameters
- Die attachment
- Wire bonding
- Glob top
- Balling
- Quality control of balling
- Electr(on)ical tests of MCM's

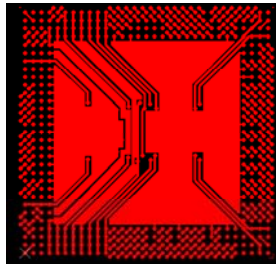


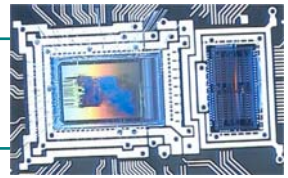
MCM: optimisation of PCB

Problem: as thin as possible and no warpage

- **Normal material (FR4) has glass transition temperature of $T_g \approx 120°C$**
- **Curing the glob top needs 150°C**
- **Isola Duraver 117 has a $T_g > 160°C$**
- **Tests with Boards of 0.8 and 1.0 mm thickness**
- **meshed and solid version of ground layer**

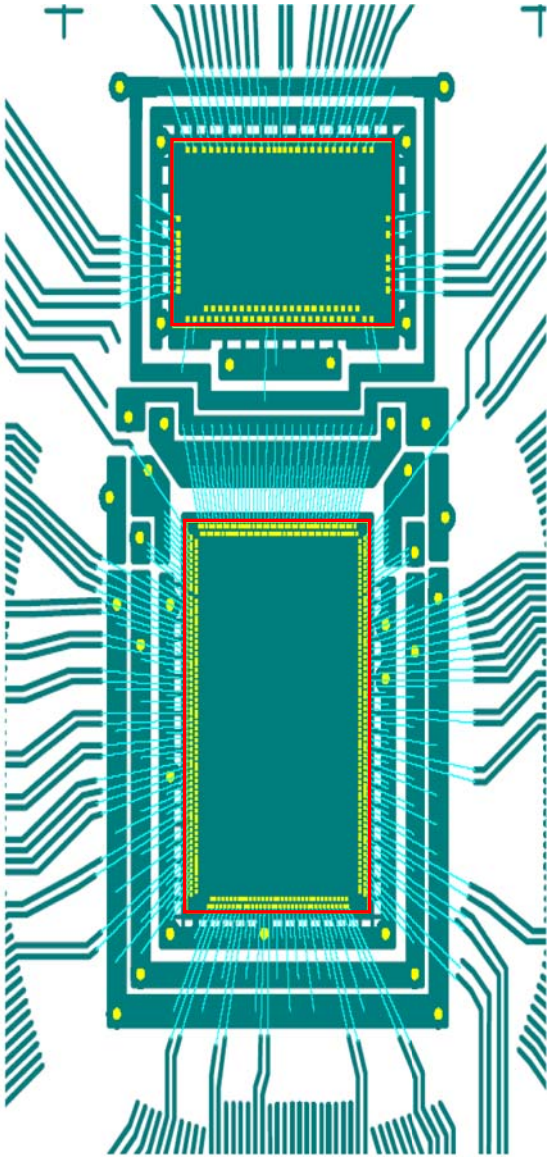


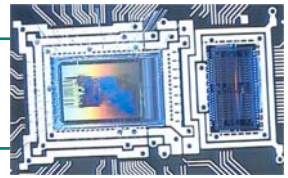




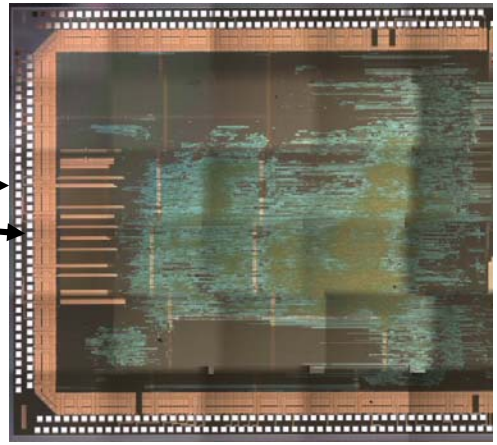
MCM: Die attachment

- **TRAP-Chip 7.4∗5.0 mm²**
  PASA-Chip 5.0∗3.4 mm²
- **Silver glue for attachment to ground**
- **both chips as near as possible together for cross links**
- **Problems:**
  - squeeze out of glue may give short circuits
  - Positioning of chips < ± 60 µm
  - warpage by curing **(20 min at 120°C)**
- **Solution (for 0.8 and 1 mm PCB):**
  - Screen printing - not dispensing glue
  - Definition of a critical distance between landing of chip and next printed wire (150 µm)

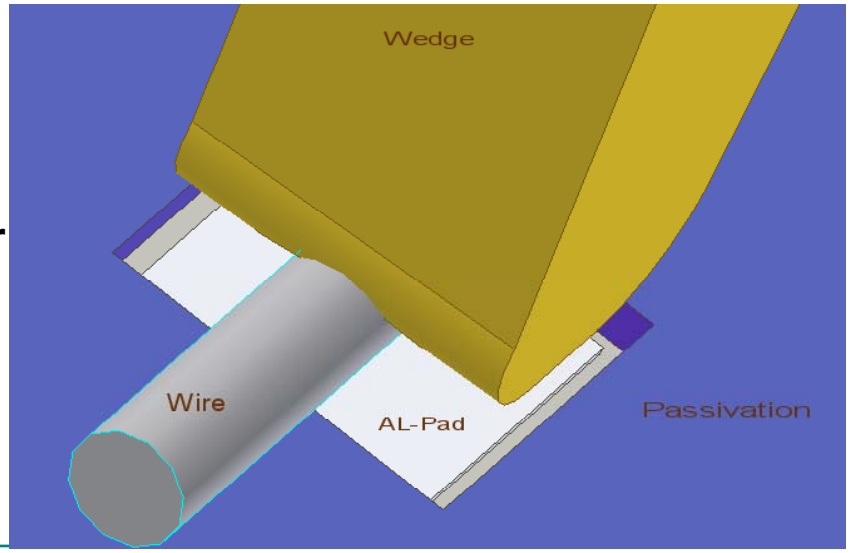


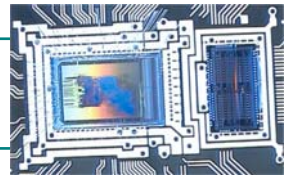


Wire bonding

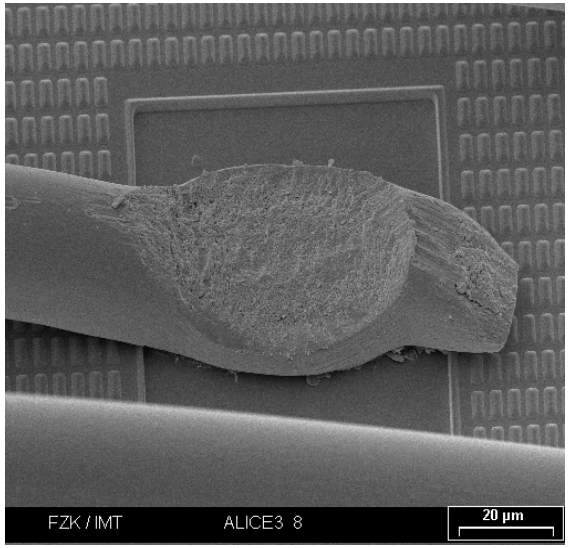


- **Bond pads of the chips 70 x 70 μm², pitch 110 μm, and staggered in 2 rows**
- **Caveats:**
  - **The wedge size have to fit to the size of the pad - otherwise passivation leads to poor joints**
  - **Position tolerance t of bond head ($t_{IPE} \approx 3\mu m$)**
  - **Select wire diameter w (22.5 - 25 μm) optimal wire diameter: pad size - 2·t > bond length ≈ 2.4·w**
  - **Tolerance of bond position may be larger at edges of bond field!!**

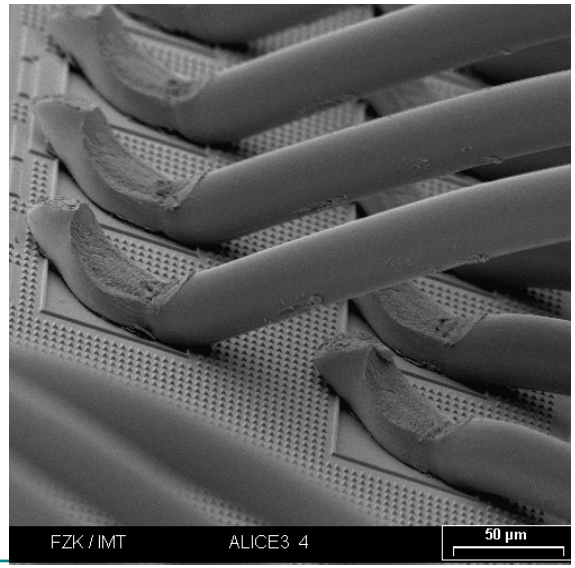


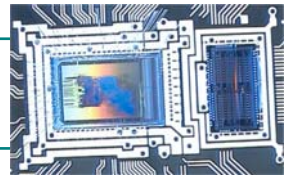


Wire bonding



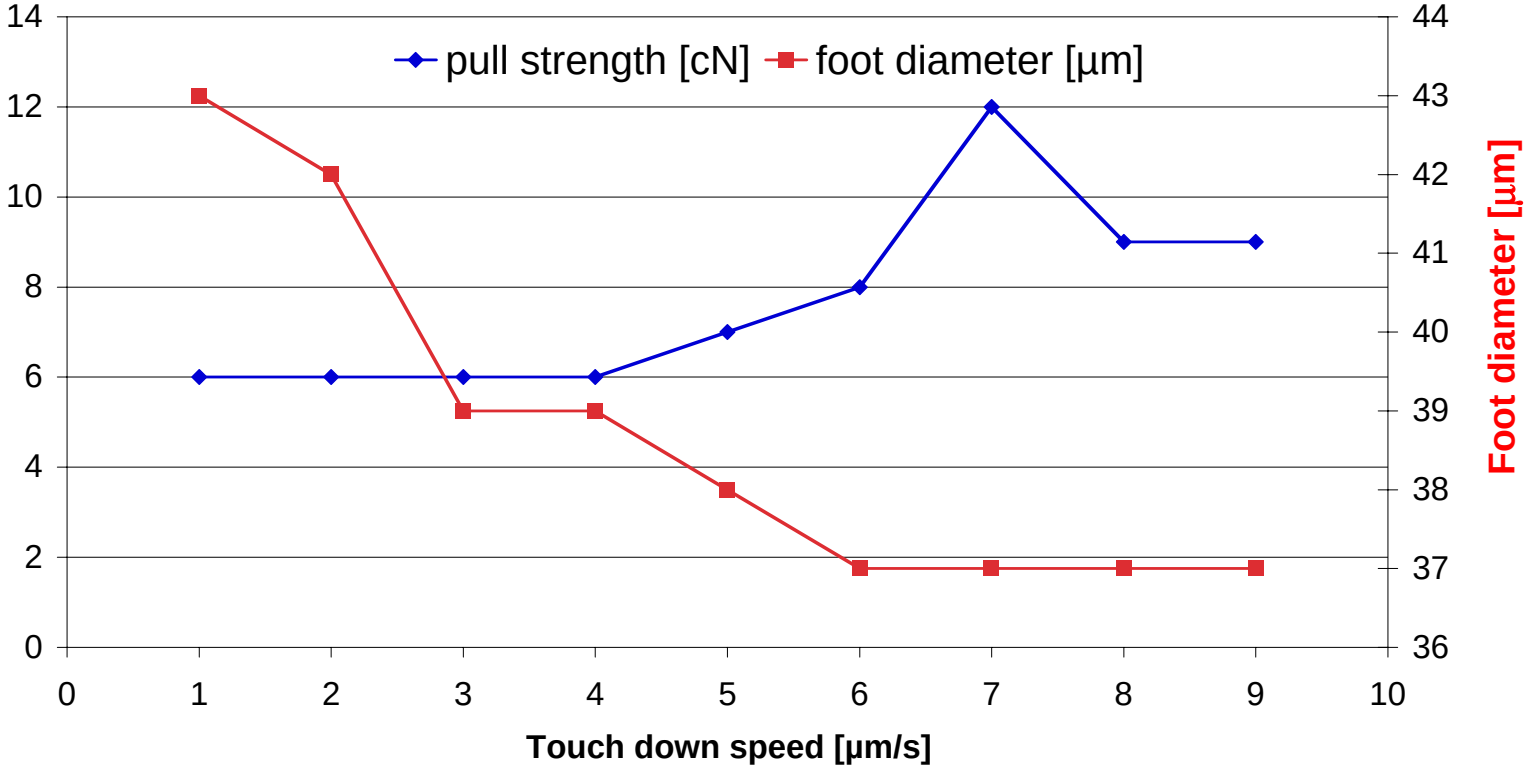
- **Some typical bonds on the TRAP chip**
- **Also exact double row bonding**
- **Many more parameters define the bond process:**
  - Speed of bond head at touch down
  - Used Ultra Sound power for bonding
  - Elasticity of bond pad support (PCB or Si)
  - Bond angle
  - Size of wire loop, . . .
- **Especially complicated for bonds over different heights: chip - chip, chip - PCB and different materials**
- **Individual optimisation is necessary!**
  - **New bond control:** measuring the bond resonance parameters and regulating the US-power!!!





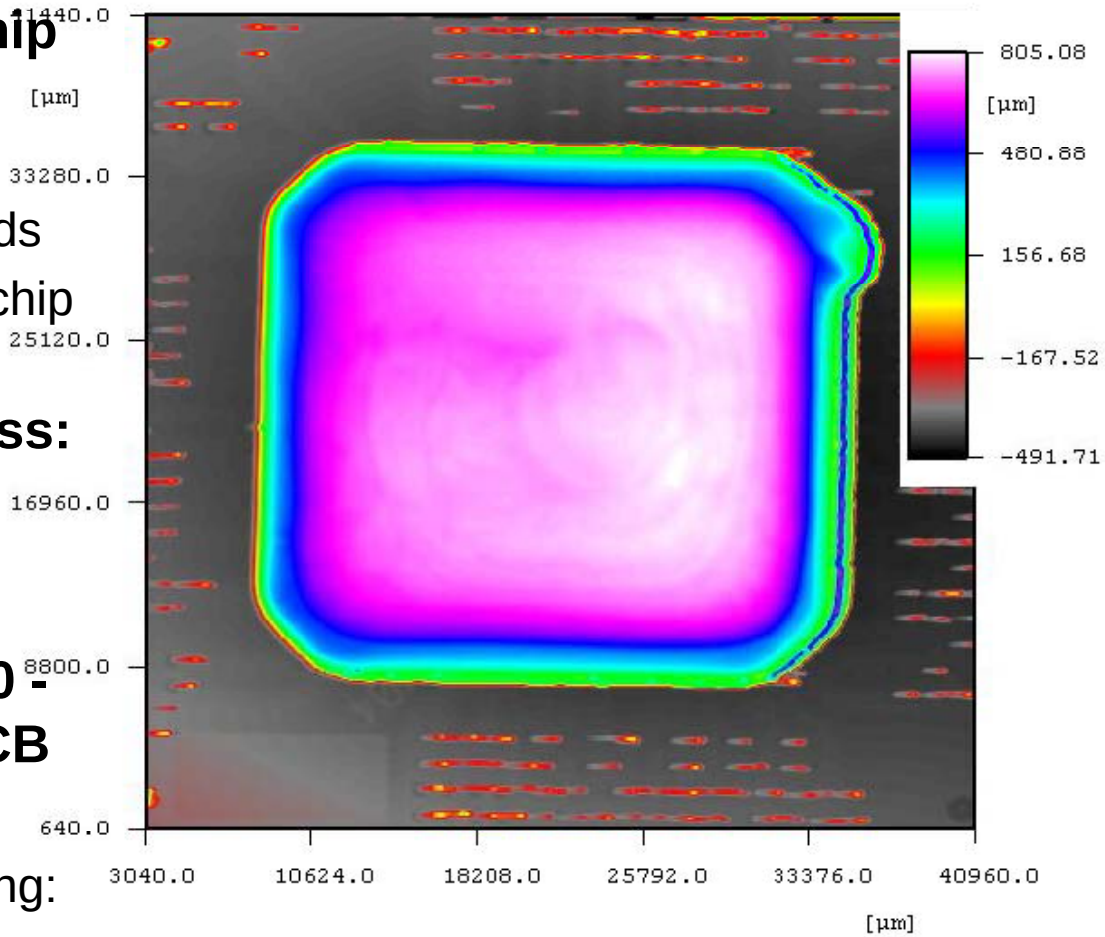
Destructive bond testing with pull tester

- **bond strength for TRAP chip and 25 µm Al bonds 10±2 cN pull test**



MCM: Glob Top

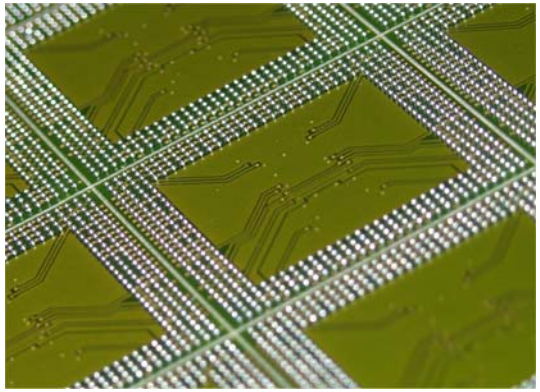
- **Protecting the bonds and the chip**
  - Medium coefficient of thermal expansion (80 ppm)
  - but low E-modulus protecting bonds
  - small max. particle size (pitch on chip is 110 µm)
- **Recommended minimal thickness:**
  300 µm chip height +
  250 µm bond loop height +
  250 µm protective top layer
- **Problem warpage by curing (120 - 150 °C) -> layout changes on PCB**
  - Now warpage < 100 µm:
  - Could be compensated by soldering: reduces height of balls by 300 µm



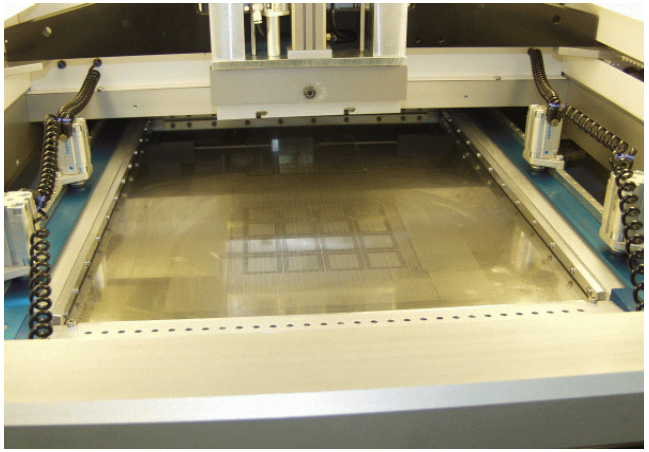
MCM: Balling

1. **Flux (Solder Paste)**
   - Screen (Stencil)
   - Pin transfer
   - Dispenser
   - Flux jet
2. **Ball placement**
   - Gravity transfer
   - Vacuum transfer
   - Solder jet
   - Screen paste
   - Dispense paste
3. **Inspection**
   - Ball count
   - Location
   - Quality
4. **Reflow**
   - IR oven
   - Vapor phase
   - Forced convection

- **Tested and rejected methods**
- **finally adopted method**

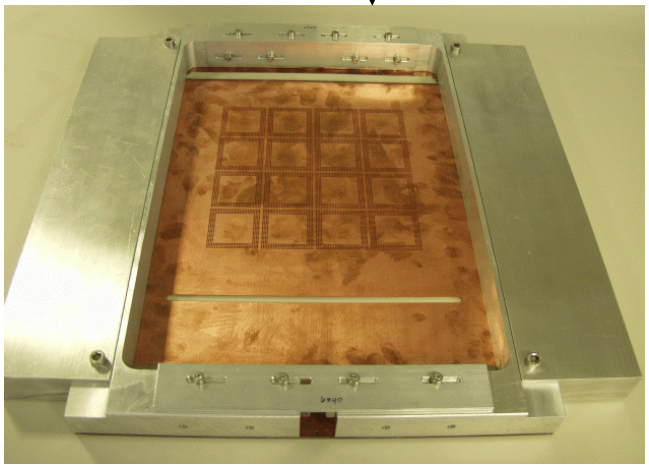


432 balls per MCM,
6912 balls per substrate



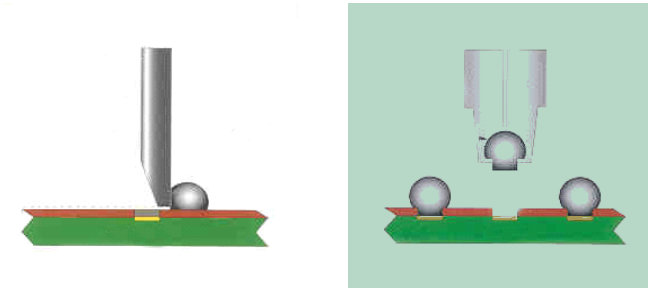
Stencil printer

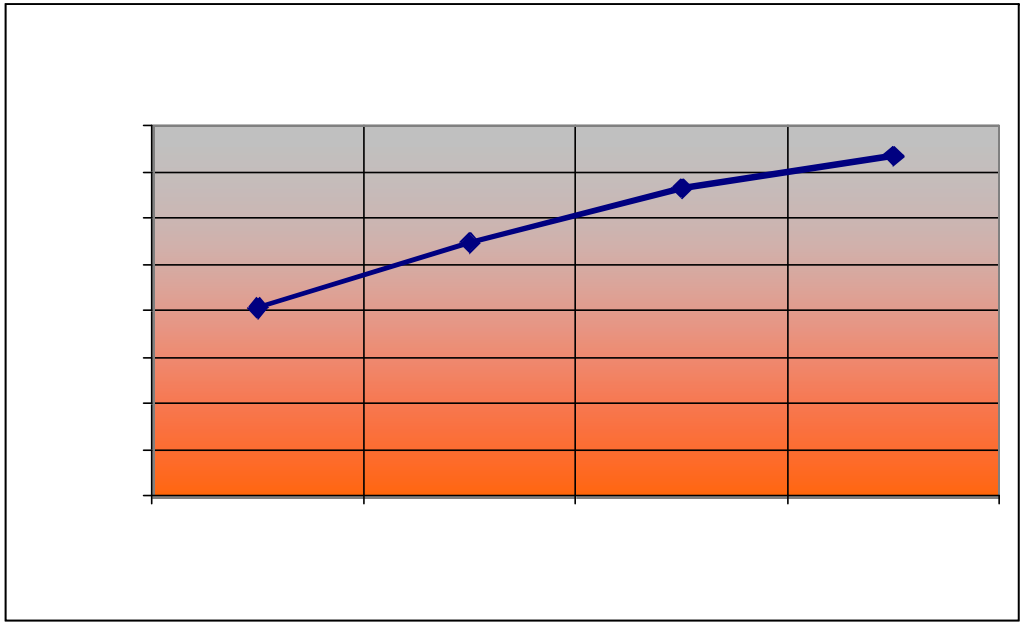
Stencil for ball transfer



MCM: Quality test of Balling

- Problem at beginning: Low shear forces required to rip balls off

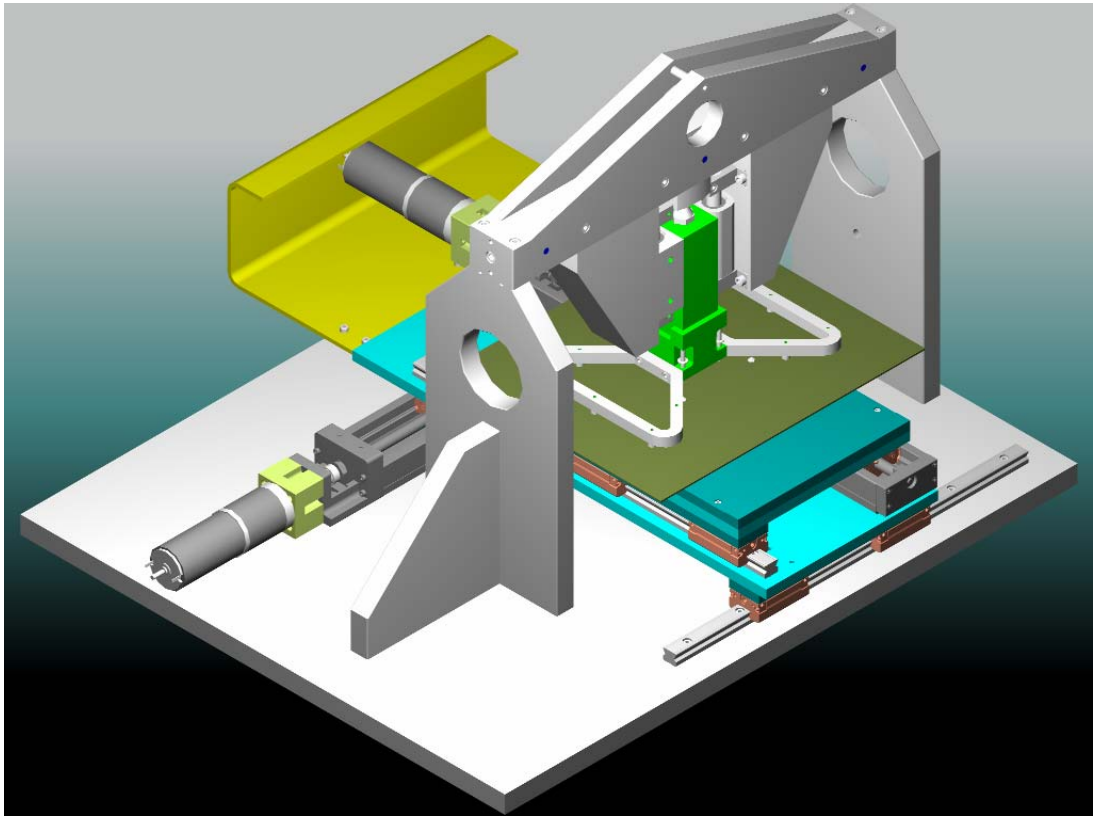




➡ Balls to small, new MCM and ROB layout with increased Pad Size

➡ solder reflow temperature profile and convection air flow !!!
(vapor oven and IR-oven not suited for balling)

MCM electronically testing

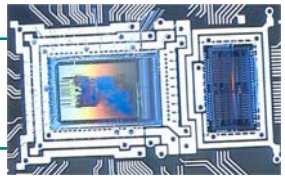


Development of an automatic test-station (finished last week):

- **Test of 16 MCM modules**
- **completely packaged**
- **incl. balls**

Readout board

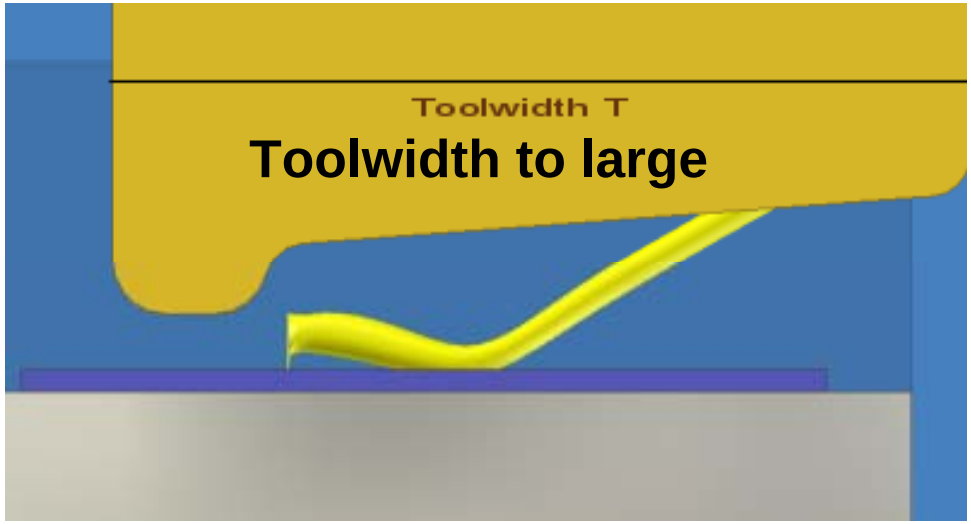
- **500 ∗ 300 mm^2 and 0.8 - 1 mm thick, ev. new carbon filled PCB**
- **17 MCM's and 1000 passive components**
- **Very delicate handling**
- **Automatic quality test optically and electrically within a SPEA flying needle prober**
- **Electronic tests and burn-in tests are under preparation**

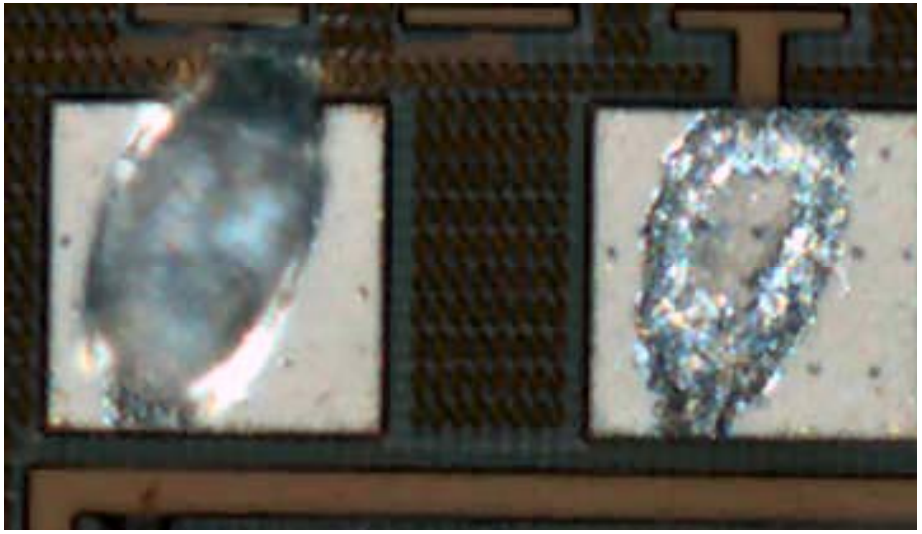


Conclusion

- **We have learned a lot - that was our intention**
  - All processes seems to be under control
  - But tests over large numbers (preproduction run) have to be done
  - Warpage was the critical question
- **Critical law of large numbers**
  - 60 000 000 bonds and 30 000 000 balls
  - What may be going wrong surely goes wrong
  - Disentangling in readout boards and MCM's helped:
    Only 890 bonds and 432 balls -> good yield achievable
- **Design of packaging have normally to be started with chip design**
  - Then the job would have been easier
  - Lower number of design loops

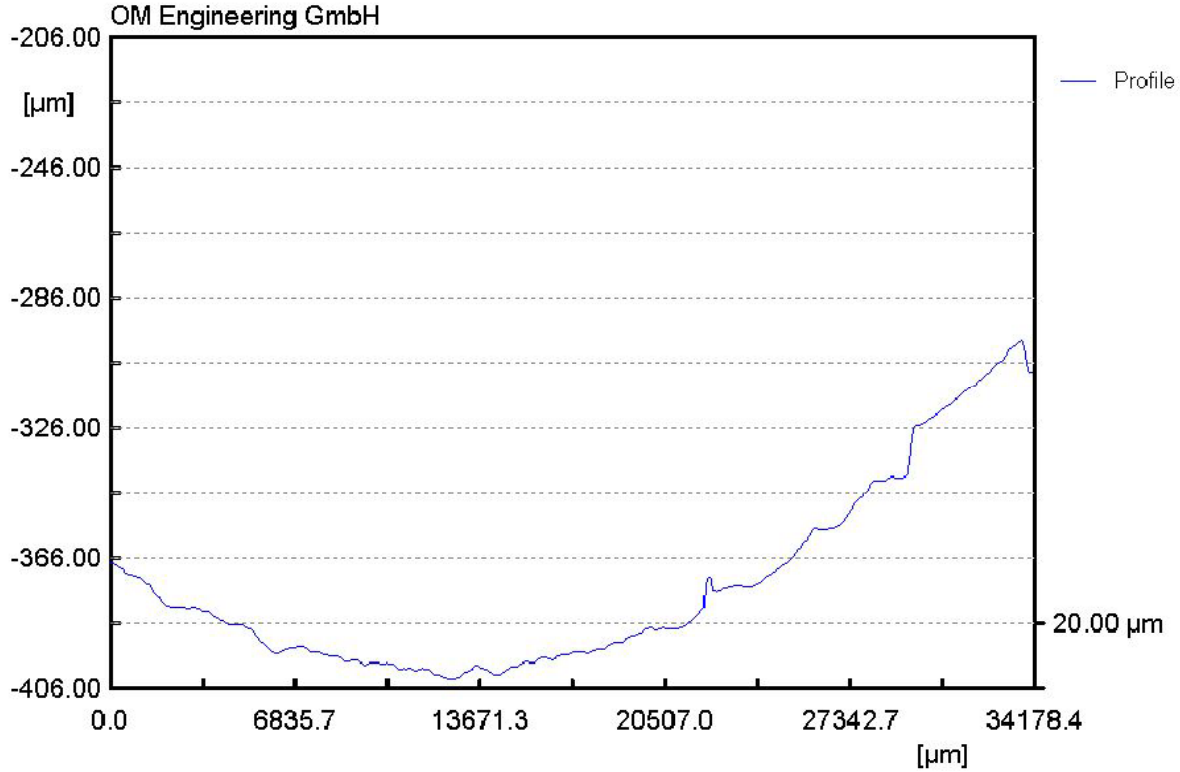
Wire bonding

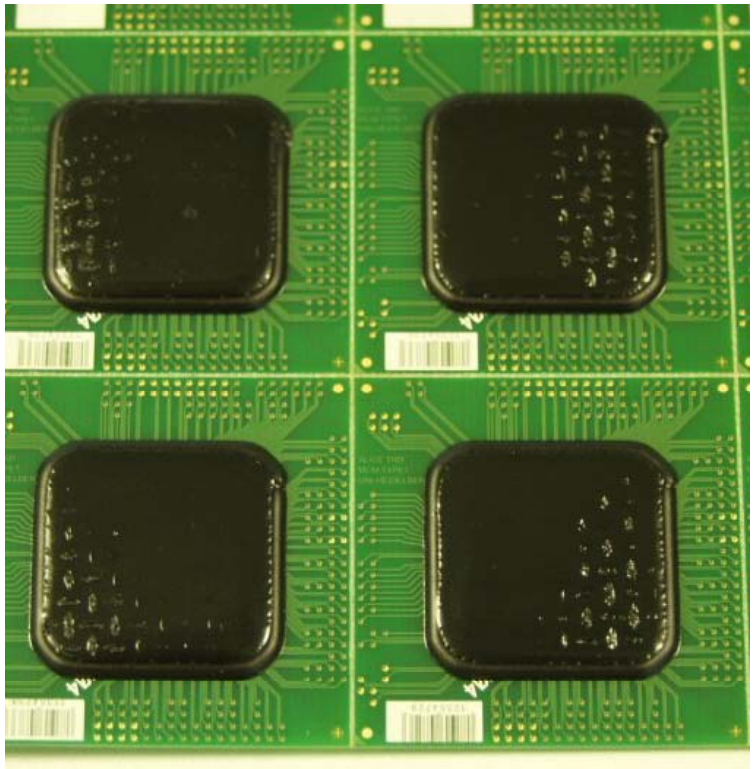




left: Footprint of an Al-bonding foot on a 70µm pad, right: welded area (removed foot). The tool used had a flat of 15µm and a front and back radius of each 25 µm

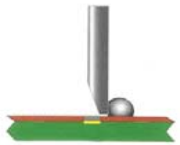
MCM: Glob Top

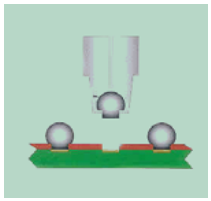




Warpage of MCM board by curing of glob top ≈ 100 ∝m

MCM Production Task: Quality control





the pull tool

pad failure,
the copper pad was torn out of the PCB